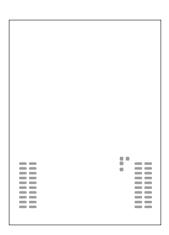
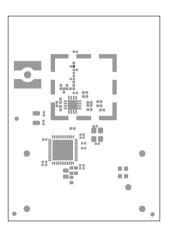


ART FILM - paste_top

ART FILM - paste_bottom

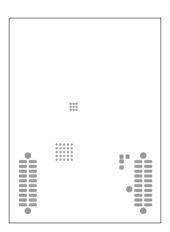


ART FILM - soldmask_top

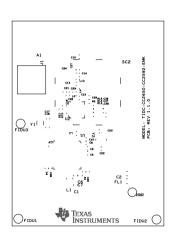


ART FILM - soldmask_top

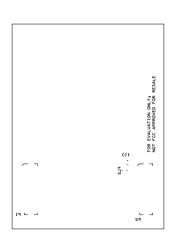
ART FILM - soldmask_bottom



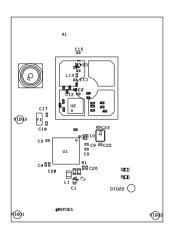
ART FILM - soldmask_bottom



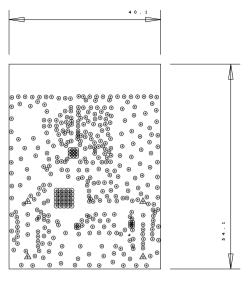
ART FILM - silk_top



ART FILM - assembly_top



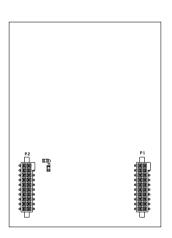
ART FILM - assembly_top



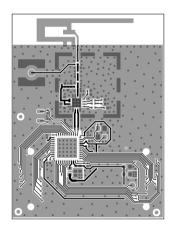
D	RILL CHART: TO	OP to BOTTOM	
AL	L UNITS ARE I	N MILLIMETER	:S
FIGURE	SIZE	PLATED	QTY
•	0.2	PLATED	367
•	0.2	PLATED	34
+	0.9	PLATED	1
A	1.5	NON-PLATED	4
A	1.5	NON-PLATED	4

* SURFACE - AIR 0 MM
L1: TOP CONDUCTOR - COPPER 0.035 MM
* DIELECTRIC - FR-4 0.175 MM
L2: L2 CONDUCTOR - COPPER 0.018 MM
DIELECTRIC - FR-4 1.14 MM
L3: L3 CONDUCTOR - COPPER 0.018 MM
DIELECTRIC - FR-4 0.175 MM
L4: BOTTOM CONDUCTOR - COPPER 0.035 MW
* SURFACE - AIR 0 MM

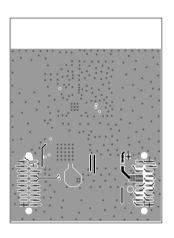
DESIGN CROSS SECTION CHART TOTAL THICKNESS 1.596 MM ART FILM - assembly_bot_mirror



ART FILM - assembly_bot_mirror

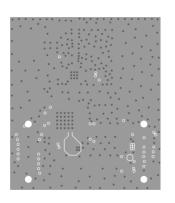


ART FILM - Top

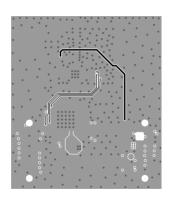


ART FILM - Bottom

ART FILM - L2



ART FILM - L2



ART FILM - L3

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